

## VLP Latch 240 Ckt Vertical Pressfit DDR2 Dimm

### 1.0 SCOPE

This Product Specification covers the 1.00 mm centerline gold plated DDR2 Dimm connector with vertical compliant termination to mate with 1.27 +/- 0.10 thick memory modules.

### 2.0 PRODUCT DESCRIPTION

#### 2.1 PRODUCT NAME AND SERIES NUMBER (S)

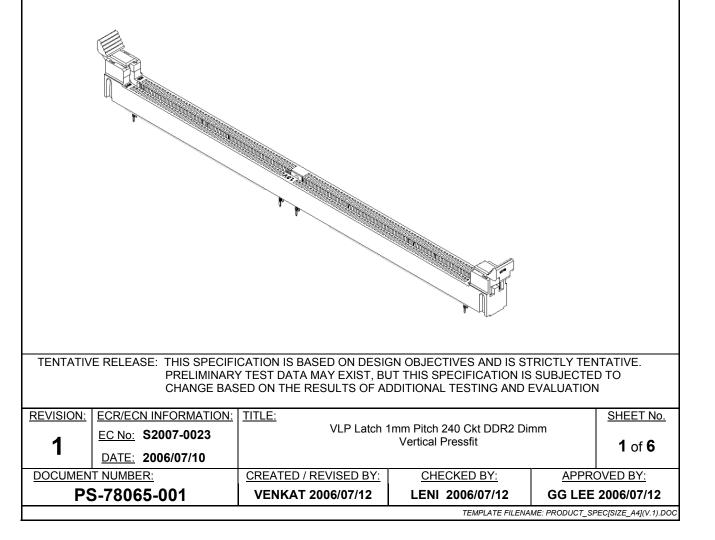
<u>Part Number</u>	Product Descriptions
78065	VLP Latch 1mm Pitch 240 Ckt Vertical Press fit DDR 2 DIMM

#### 2.2 DIMENSIONS, MATERIALS, PLATINGS AND MARKINGS

See the appropriate Sales Drawings for information on dimensions, materials, plating and markings, recommended module outlines and footprint Specifications.

### 2.3 SAFETY AGENCY APPROVALS

UL File	:	TBA
CSA File	:	TBA





### 3.0 APPLICABLE DOCUMENTS AND SPECIFICATIONS

The following documents are part of this specification between the requirements of this specified herewith. In the event of conflict between the requirements of this specification and the product drawings, the product drawings shall take precedence. In the event of conflict between the requirements of this specification and reference documents, this specification shall take precedence.

#### 4.0 RATINGS

4.1 VOLTAGE 30 Volts AC (RMS) / DC

## 4.2 CURRENT

0.5 Amps/ pin

## 4.3 FIELD LIFE AND TEMPERATURE

Field Life:3 yearsField Temperature:60°C

## **4.4 OPERATING TEMPERTURE**

-55°C ~ +85°C

#### 5.0 PERFORMANCE

#### **5.1 ELECTRICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION		R	EQUIREME	NT
1	Contact Resistance (Low Level)	Mate connectors: apply a maximum voltage of 20 mV and a current of 100 mA.30 milliohms Max Initi ∆R : 20 milliohms Max DiscreteEIA-364-23				
2	Insulation Resistance	Unmate & unmount connectors: apply a voltage of 500 VDC between adjacent terminals and between terminals to ground. EIA-364-21				
3	Dielectric Withstanding Voltage	Apply 500 VAC for 1 minute adjacent terminals of an uni connector. EIA-364-20	No break	down		
SION:	ECR/ECN INFORMATION:	TITLE:				SHEET
1 <u>EC No:</u> S2007-0023 <u>DATE:</u> 2006/07/10			mm Pitch 240 Cl Vertical Pressfi		mm	<b>2</b> of <b>6</b>
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VENKAT 2006/07/12

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## **5.2 MECHANICAL REQUIREMENTS**

ITEM	DESCRIPTION	TEST CONDITION		R	EQUIREME	NT	
4	Module Insertion Force (w/ Latches)	Insert a PCB at a rate of 25 inch) per minute. Latches sh included in the test. See Sal PCB/ Module details.	all be				
5	Terminal Retention Force	Axial pullout force on the ter housing at a rate of $25 \pm 6$ n inch) per minute. EIA 364-29	nm (1 ± ¼	Contact: 0.30kgf Min.			
6	Durability (Preconditioning)	Mate and unmated connector cycles at a maximum rate of minute prior to Environment	f 10 cycles per		Resistance: hilliohms Ma	x.	
7	Durability	Mate and unmated connector cycles at a maximum rate of minute prior to Environment	f 10 cycles per		Resistance: hilliohms Ma	x.	
8	Vibration	EIA-364-28, Test Condition Power Spectral Density: 0.0 Overall rms: 3.10g Min Duration: 15 mins in each X	2g²/ Hz	Contact Resistance: $\Delta R$ : 20 milliohms Max.			
9	Shock (Mechanical)	Mate connectors and shock ½ sine wave (11 millisecond the ±X, ±Y, ±Z axis (18 sho Module card height 30mm, 35 ± 5g. EIA-364-27	ds) shocks in cks total).	Contact Resistance: ∆R : 20 milliohms Max.			
10	Module Ripout Force	Pull up from the center of the the latches closed at a rate of min. (1 $\pm$ 1/4 inch).		9.1kgf (20lbs) min. retention force of the module in connector with no damage			
11	Reseating	Manually mate and unmate t with module card for 3 cycles		No dama	ge.		
12	Compliant pin insertion force to PCB (single)	Insert compliant pin into app hole with min. hole size 0.5 of 25+/-6mm per minute.		4.5kgf (10lbs) max. per pin.			
13	Compliant pin retention force (single)	Pull compliant pin axially from PCB with max. hole size 0.64mm at a rate of 25+/- 6mm per minute.			per pin.		
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	EC No: <b>\$2007-0023</b>	VLP Latch 1mm Pitch 240 Ckt DDR2 Dimm Vertical Pressfit		<b>3</b> of			
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## 5.2 MECHANICAL REQUIREMENTS (CON'T)

ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
14	Latch Overstress Force		3.5kgf (7.7lbs) min. force held for 10 sec. With no damage.
15	Latch Actuation Force	rate of 25 $\pm$ 6 mm/mm (1 $\pm$ % mcm) with	The force fully actuate the latch open shall be 4.5kgf (10lbs) max. per latch.

### **5.3 ENVIRONMENTAL REQUIREMENTS**

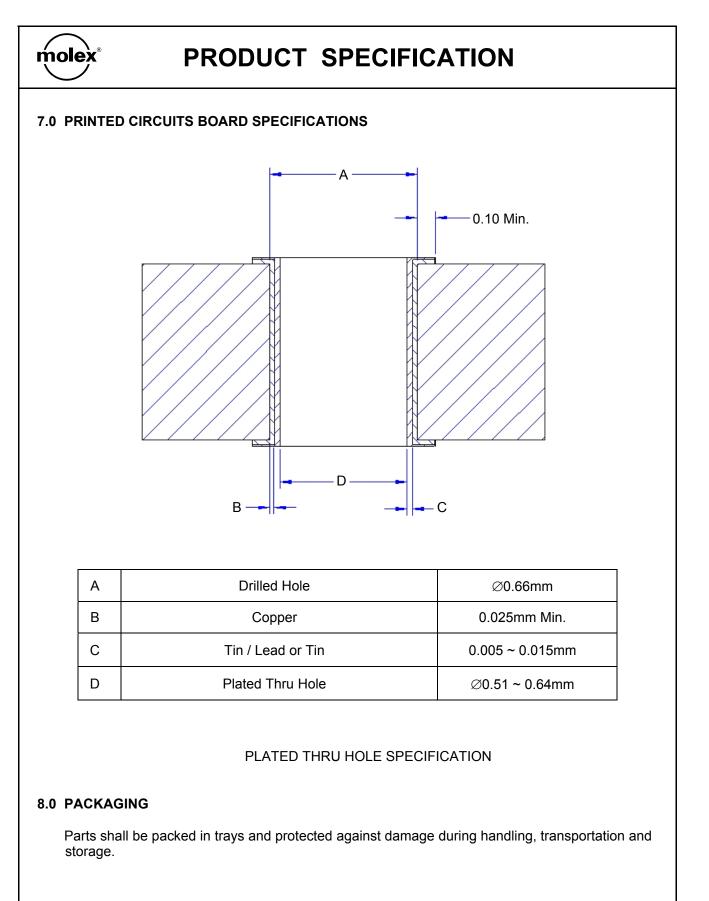
ITEM	DESCRIPTION	TEST CONDITION	REQUIREMENT
16	Shock (Thermal)	Mate connectors; expose to 5 cycles of:   Temperature °C Duration (Minutes)   -55 ±0/-3 30   +25 ±10 5 MAXIMUM   +85 ±3/-0 30   +25 ±10 5 MAXIMUM   EIA-364-32	Contact Resistance: ∆R : 20 milliohms Max. Appearance: No Damage
17	Temperature Life (Preconditioning)	Mate connectors; expose to: 24 hours at 105 ± 3°C Per EIA-364-17	Contact Resistance: ∆R : 20 milliohms Max. Appearance: No Damage
18	Temperature Life	Mate connectors; expose to: 48 hours at 105 ± 3°C Per EIA-364-17	Contact Resistance: ∆R : 20 milliohms Max. Appearance: No Damage
19	Temperature Rise	Mate the connectors, series 6 contacts and measure the temperature rise at the rated current of 0.5A after 4 hours.	Maximum Temperature Rise: 30 °C above ambient.
20	Cyclic Temperature & Humidity	Cycle the connector between 25°C, with RH of 90-98% and 65°C, with RH of 80- 98%. Ramp times should be 2.5hours and dwell times should be 2.5hours. Dwell times start when the temperature and humidity have stabilized within the specified levels. Expose to 10 days. Per EIA-364-31, Method III	Contact Resistance: ∆R : 20 milliohms Max. Appearance: No Damage

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## 6.0 TEST SEQUENCE

	escription					Test C	Broup					
	uence	1	2	3	4	5	6	7	8	9	10	
Initial Cont Resistance		1	1	1		1						
Durability (Precondit	ioning)	2	2	2								
Durability						2						
Insulation	Resistance				1 5							
Dielectric \ Voltage	Vithstand				2 6							
Contact Re	esistance	4 6	4 6 8	4 6 8		3						
Temperatu (Precondit	ire Life ioning)		-	3								
Temperatu	ıre Life	3										
Thermal S	hock		3		3							
Mechanica	I Shock			7								
Vibration				5								
Reseating		5	7									
Cyclic Ten Humidity	ıp &		5		4							
Temperatu	ire Rise						1					
Module Ins Force	sertion							1				
Module Ri	pout Force							2				
Compliant Insertion fo	pin prce to PCB								1			
Compliant Retention	· ·								2			
Contact Re	etention									1		
Latch Actu	ation Force										1	
Latch Ove Force	rstress										2	
Sample Si Group	ze per Test	5	5	5	5	5	5	5	5	5	5	
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